

DEVICE FOR LIQUID TREATMENT OF WAFER-SHAPED ARTICLES

Abstract

The invention relates to a device for liquid treatment of a defined area of a wafer-shaped article, especially of a wafer, in which a mask is kept at a defined short distance to the wafer-shaped article such that liquid can be retained between the mask and the defined area of the wafer-shaped article by capillary forces.

This Sheet Has Been Replaced

